

[MOLD AND METHOD OF MOLDING SEMICONDUCTOR DEVICES]

Abstract

A mold for molding semiconductor devices mounted on a package substrate is provided. The mold comprises a top mold and a bottom mold. The top mold has a top runner, at least a first dummy runner and a plurality of mold cavities. The first dummy runner connects with the top runner and the top runner extends into a space between the mold cavities. The mold cavities for accommodating the semiconductor devices are connected to the top runner. The bottom mold has a bottom runner and at least a second dummy runner. The second dummy runner connects with the bottom runner. The second dummy runner is above but separated from the first dummy runner by the package substrate.